U.S. PTO 12/228378 08/12/2008

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PATEN	<u>rs</u> IIII III III III III III III III III
To the Director of the U.S. Patent and Trademark Office: Plea	
1. Name of conveying party(ies)	2. Name and address of receiving party(les)
Se-Young Lee You-Seung Jin	Name: Samsung Electronics Co., Ltd.
Geon-Woo Park	Internal Address:
A. Patent Application No.(s)	Street Address: _416, Maetan-dong,
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved: 1
Name:David M. Mello	7. Total fee (37 CFR 1.21(h) & 3.41) \$_40.00
Internal Address:	Authorized to be charged by credit card
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Street Address: Mills & Onello LLP	Enclosed
Eleven Beacon Street, Suite 605	None required (government interest not affecting title
City: Boston	8. Payment Information
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Phone Number: (617) 994-4900	Expiration Date 11/08
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PATENT REEL: 021448 FRAME: 0622

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Reference No.: SAM-1285

ASSIGNMENT

We, Se-Young Lee, of 379-4 Songjuk-dong, Jangan-gu, Suwon-si, Gyeonggi-do, Republic of Korea; You-Seung Jin, of 1023-5 Daerim 2-dong, Yeongdeungpo-gu, Seoul, Republic of Korea; Geon-Woo Park of 246-504, Hwanggol Ssangyong Apt., 1052-2 Yeongtong-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea having invented improvements in SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING THE SEMICONDUCTOR DEVICE, FLIP CHIP PACKAGE HAVING THE SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURING THE FLIP CHIP PACKAGE described in an application for Letters Patent of the United States, executed by us on even date herewith, for good and valuable consideration, receipt of which is hereby acknowledged from Samsung Electronics Co., Ltd., a Korean corporation having a place of business at 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea (and hereinafter called the Assignee, which term shall include its successors and assigns), do hereby sell, assign and transfer unto the Assignee our entire right, title, and interest in and throughout the United States of America (including its territories and dependencies) and all countries foreign thereto, in and to and under said application (which term shall include hereinafter where the context so admits all divisional, continuing, reissue and other patent applications based thereon) and the inventions (which term shall include each and every such invention, or part thereof) therein described, and any and all patents and like rights of exclusion (including extensions thereof) of any country which may be granted on or for said inventions or on said application;

And for the same consideration We do also hereby sell, assign, and transfer unto the Assignee, all our rights under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, and all other treaties of like purpose in respect of said inventions and said application, and We do hereby authorize the Assignee to apply in our name or its own name or its designee for patents and like rights of exclusion on or for said inventions in all countries, claiming (if the Assignee so desires) the priority of the filing date of said application under the provisions of said Convention, Treaty or any such other Convention or Treaty;

And for the same consideration, We do hereby agree for ourselves and for our heirs, executors, and administrators, promptly upon request of the Assignee to execute and deliver without further compensation any power of attorney, assignment, original, divisional, continuing, reissue or other application or applications for patent or patents or like rights of exclusion of any country, or other lawful documents and any further assurances that may be deemed necessary or desirable by the Assignee, fully to secure to it said right, title, and interest as aforesaid in and to said inventions, applications, and said several patents and like rights of exclusion (including extensions thereof) or any of them, all, however, at the expense of the Assignee, its successors, or assigns;

And We do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and the corresponding Official of each country foreign thereto to issue to the Assignee, any and all patents and like rights of exclusion which may be granted in any country upon said United States application on or for said inventions;

And We do hereby covenant for ourselves and our legal representatives and agree with the Assignee, that We have granted no right or license to make, use, or sell said inventions to anyone except the Assignee, that prior to the execution of this deed our right, title, and interest in and to said inventions has not been otherwise encumbered by us, and that We have not executed and will not execute any instruments in conflict herewith.

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Reference No.: SAM-1285

First or Sole Inventor:

Signature:

Se-Voung Lee

Date: 3//July/2008

Second Joint Inventor:

Signature:

You-Seung Jin

Date: 31 Jul 2008

Third Joint Inventor:

Signature:

Geon-Woo Park

Date: 4 Aug 2000

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